

Low On Resistance (4 Ω) On Resistance Flatness 0.2 Ω

44 V Supply Maximum Ratings

Fully Specified @ ±5 V, +12 V, ±15 V

Ultralow Power Dissipation (18 µW)

and ADG431/ADG432/ADG433

±15 V Analog Signal Range

Continuous Current 100 mA

Fast Switching Times

TTL/CMOS Compatible

FEATURES

ESD 2 kV

t_{on} 70 ns

t_{off} 60 ns

APPLICATIONS

Relay Replacement

Audio and Video Switching

Automatic Test Equipment

Precision Data Acquisition

Battery Powered Systems

Communication Systems

Sample Hold Systems

PBX, PABX Systems

Avionics

LC²MOS 5 Ω R_{on} SPST Switches

ADG451/ADG452/ADG453

FUNCTIONAL BLOCK DIAGRAMS



The ADG453 exhi

The ADG453 exhibits break-before-make switching action for use in multiplexer applications. Inherent in the design is low charge injection for minimum transients when switching the digital inputs.

PRODUCT HIGHLIGHTS

- 1. Low R_{ON} (5 Ω max)
- 2. Ultralow Power Dissipation
- Extended Signal Range The ADG451, ADG452 and ADG453 are fabricated on an enhanced LC²MOS process giving an increased signal range that fully extends to the supply rails.
- 4. Break-Before-Make Switching This prevents channel shorting when the switches are configured as a multiplexer. (ADG453 only.)
- 5. Single Supply Operation For applications where the analog signal is unipolar, the ADG451, ADG452 and ADG453 can be operated from a single rail power supply. The parts are fully specified with a single +12 V power supply and will remain functional with single supplies as low as +5.0 V.

 Dual Supply Operation For applications where the analog signal is bipolar, the ADG451, ADG452 and ADG453 can be operated from a dual power supply ranging from ±4.5 V to ±20 V.

GENERAL DESCRIPTION

The ADG451, ADG452 and ADG453 are monolithic CMOS devices comprising four independently selectable switches. They are designed on an enhanced LC^2MOS process that provides low power dissipation yet gives high switching speed and low on resistance.

Pin Compatible Upgrade for ADG411/ADG412/ADG413

The on resistance profile is very flat over the full analog input range ensuring excellent linearity and low distortion when switching audio signals. Fast switching speed coupled with high signal bandwidth also make the parts suitable for video signal switching. CMOS construction ensures ultralow power dissipation making the parts ideally suited for portable and battery powered instruments.

The ADG451, ADG452 and ADG453 contain four independent single-pole/single-throw (SPST) switches. The ADG451 and ADG452 differ only in that the digital control logic is inverted. The ADG451 switches are turned on with a logic low on the appropriate control input, while a logic high is required for the ADG452. The ADG453 has two switches with digital control logic similar to that of the ADG451 while the logic is inverted on the other two switches.

Each switch conducts equally well in both directions when ON and has an input signal range which extends to the supplies. In the OFF condition, signal levels up to the supplies are blocked.

REV. A

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ADG451/ADG452/ADG453-SPECIFICATIONS¹

Dual Supply (V_{DD} = +15 V, V_{SS} = -15 V, V_L = +5 V, GND = 0 V. All specifications T_{MIN} to T_{MAX} unless otherwise noted.)

	B Version			
Parameter	+25°C	T _{MIN} to T _{MAX}	Units	Test Conditions/Comments
ANALOG SWITCH		- MAX	011105	
Analog Signal Range		V_{SS} to V_{DD}	V	
On-Resistance (R _{ON})	4.0	V _{SS} to V _{DD}	v Ω typ	$V_{\rm D} = -10$ V to +10 V, $I_{\rm S} = -10$ mA
On-Resistance (R _{ON})	4.0 5	7	$\Omega \max$	$v_{\rm D} = -10 v t0 + 10 v, 1_{\rm S} = -10 \text{ mA}$
On-Resistance Match Between	0.1	'	$\Omega \chi$ typ	$V_{\rm D} = \pm 10$ V, $I_{\rm S} = -10$ mA
Channels (ΔR_{ON})	0.1	0.5	$\Omega \max$	$v_{\rm D} = \pm 10 v, I_{\rm S} = -10 {\rm mA}$
On-Resistance Flatness $(R_{FLAT(ON)})$	0.3	0.5	$\Omega \chi$	$V_{\rm D} = -5 \text{ V}, 0 \text{ V}, +5 \text{ V}, I_{\rm S} = -10 \text{ mA}$
On-Resistance Francess (RFLAT(ON))	0.5	0.5	$\Omega \max$	$v_{\rm D} = -3 v, 0 v, +3 v, t_{\rm S} = -10 \text{ mA}$
LEAKAGE CURRENTS ²				
Source OFF Leakage I _S (OFF)	± 0.02		nA typ	$V_{\rm D} = \pm 10 \text{ V}, V_{\rm S} = \pm 10 \text{ V};$
Source of F Leakage 15 (OFF)	± 0.5	± 2.5	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	± 0.02	±2.0	nA typ	$V_{\rm D} = \pm 10 \text{ V}, V_{\rm S} = \pm 10 \text{ V};$
Drum Off Leanage ID (011)	± 0.5	± 2.5	nA max	Test Circuit 2
Channel ON Leakage I _D , I _S (ON)	± 0.04	± 2.0	nA typ	$V_D = V_S = \pm 10 \text{ V};$
Chamiler Or v Leanage 1D, 15 (Or v)	±0.04 ±1	± 5	nA typ	Test Circuit 3
DIGITAL INPUTS				
Input High Voltage, V _{INH}		2.4	V min	
Input Low Voltage, V _{INL}		0.8	V max	
Input Low Voltage, V _{INL}		0.0	v max	
	0.005		uA two	$V_{\rm exp} = V_{\rm exp}$ or $V_{\rm exp}$ All Others = 2.4 V
I _{INL} or I _{INH}	0.005	± 0.5	μA typ μA max	$V_{IN} = V_{INL}$ or V_{INH} , All Others = 2.4 V or 0.8 V Respectively
DYNAMIC CHARACTERISTICS ³			P******	
	70		na trin	B 200 O C 25 mE
t _{ON}	70 180	220	ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
+	180 60	220	ns max	$V_{\rm S} = \pm 10$ V; Test Circuit 4
t _{OFF}	60 140	100	ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
Brook Bofore Make Time Delay t	140	180	ns max	$V_{\rm S} = \pm 10$ V; Test Circuit 4
Break-Before-Make Time Delay, t _D		F	ns typ	$R_{L} = 300 \Omega, C_{L} = 35 pF;$
(ADG453 Only)	5	5	ns min	$V_{S1} = V_{S2} = +10$ V; Test Circuit 5
Charge Injection	20		pC typ	$V_{\rm S} = 0 \text{ V}, \text{ R}_{\rm S} = 0 \Omega, \text{ C}_{\rm L} = 1.0 \text{ nF};$
Charge injection	20 30		pC typ pC max	Test Circuit 6
OFF Isolation	50 65		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$;
	00		unityp	Test Circuit 7
Channel-to-Channel Crosstalk	-90		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$;
			-	Test Circuit 8
C _s (OFF)	15		pF typ	f = 1 MHz
$C_{\rm D}$ (OFF)	15		pF typ	f = 1 MHz
$C_D, C_S(ON)$	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$ Digital Inputs = 0 V or 5 V
I _{DD}	0.0001		μA typ	
	0.5	5	μA max	
I _{SS}	0.0001		μA typ	
	0.5	5	μA max	
IL	0.0001		μA typ	
~	0.5	5	µA max	
I_{GND}^{3}	0.0001	-	μA typ	
	0.5	5	μA max	

NOTES

¹Temperature range is as follows: B Version: -40 °C to +85 °C. ²T_{MAX} = +70 °C

³Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

Single Supply $(V_{DD} = +12 V, V_{SS} = 0 V, V_L = +5 V, GND = 0 V. All specifications T_{MIN}$ to T_MAX unless otherwise noted.)

	B Version			
Parameter	+25°C	T _{MIN} to T _{MAX}	Units	Test Conditions/Comments
ANALOG SWITCH		- MAA		
		0 V to V	v	
Analog Signal Range On-Resistance (R _{ON})	6	0 V to V_{DD}		$V_{\rm D} = 0$ V to 10 V, $I_{\rm S} = -10$ mA
On-Resistance (R _{ON})	6	10	Ωtyp	$V_{\rm D} = 0$ V to 10 V, $I_{\rm S} = -10$ mA
	8	10	Ω max	
On-Resistance Match Between	0.1		Ωtyp	$V_{\rm D} = 10$ V, $I_{\rm S} = -10$ mA
Channels (ΔR_{ON})	0.5	0.5	Ω max	
On-Resistance Flatness (R _{FLAT(ON)})	1.0	1.0	Ω typ	$V_{\rm D} = 0 \text{ V}, +5 \text{ V}, \text{ I}_{\rm S} = -10 \text{ mA}$
LEAKAGE CURRENTS ^{2, 3}				
Source OFF Leakage I _S (OFF)	±0.02		nA typ	$V_{\rm D} = 0 \text{ V}, 10 \text{ V}, V_{\rm S} = 0 \text{ V}, 10 \text{ V};$
Source of the Leakage is (011)	± 0.5	± 2.5	nA max	Test Circuit 2
Drain OFF Leakage I_D (OFF)	± 0.3 ± 0.02	± 6.0	nA typ	$V_{\rm D} = 0 \text{ V}, 10 \text{ V}, V_{\rm S} = 0 \text{ V}, 10 \text{ V};$
Diani OITI Leanage ID (OFF)		19 F		
Channel ON Leaders I. J. (ON)	± 0.5	± 2.5	nA max	Test Circuit 2
Channel ON Leakage I_D , I_S (ON)	± 0.04		nA typ	$V_{\rm D} = V_{\rm S} = 0 \text{ V}, 10 \text{ V};$
	±1	± 5	nA max	Test Circuit 3
DIGITAL INPUTS				
Input High Voltage, V _{INH}		2.4	V min	
Input Low Voltage, V _{INL}		0.8	V max	
Input Current		0.0	V mux	
I _{INL} or I _{INH}	0.005		μA typ	$V_{IN} = V_{INL}$ or V_{INH}
IINL OF IINH	0.005	± 0.5	$\mu A max$	VIN - VINL OI VINH
		±0.0	μη παχ	
DYNAMIC CHARACTERISTICS ⁴				
t _{ON}	100		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
	220	260	ns max	$V_{\rm S} = +8$ V; Test Circuit 4
t _{OFF}	80		ns typ	$R_{L} = 300 \Omega, C_{L} = 35 pF;$
	160	200	ns max	$V_{\rm S} = +8$ V; Test Circuit 4
Break-Before-Make Time Delay, t _D	15		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
(ADG453 Only)	10	10	ns min	$V_{S1} = V_{S2} = +8 V;$
(10		Test Circuit 5
Charge Injection	10		pC typ	$V_{\rm S} = 0 \text{ V}, \text{ R}_{\rm S} = 0 \Omega, \text{ C}_{\rm L} = 1.0 \text{ nF};$
charge injection	10		P C CP	Test Circuit 6
Channel-to-Channel Crosstalk	-90		dB two	
Chamber-10-Chamber Crosstalk	-90		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz;$
C (OFF)	15		mE to m	Test Circuit 8
$C_{\rm S}$ (OFF)	15		pF typ	f = 1 MHz
$C_{\rm D}$ (OFF)	15		pF typ	f = 1 MHz
$C_{\rm D}, C_{\rm S} \left({\rm ON} \right)$	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				$V_{DD} = +13.2 \text{ V}$
				Digital Inputs = $0 \text{ V or } 5 \text{ V}$
I _{DD}	0.0001		μA typ	
±UU	0.5	5	μA typ μA max	
I.	0.0001	5		
IL		5	μA typ	V = 155 V
т 4	0.5	5	μA max	$V_{L} = +5.5 V$
I_{GND}^{4}	0.0001	-	μA typ	
	0.5	5	μA max	$V_{L} = +5.5 V$

NOTES

¹Temperature range is as follows: B Version: $-40 \,^{\circ}\text{C}$ to $+85 \,^{\circ}\text{C}$. ²T_{MAX} = $+70 \,^{\circ}\text{C}$. ³Tested with dual supplies. ⁴Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

ADG451/ADG452/ADG453-SPECIFICATIONS¹

Dual Supply (V_{DD} = +5 V, V_{SS} = -5 V, V_L = +5 V, GND = 0 V. All specifications T_{MIN} to T_{MAX} unless otherwise noted.)

	B Version			
Parameter	+25°C	T _{MIN} to T _{MAX}	Units	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		V_{SS} to V_{DD}	V	
On-Resistance (R _{ON})	7	. 33	Ω typ	$V_D = -3.5$ V to $+3.5$ V, $I_S = -10$ mA
	12	15	Ω max	
On-Resistance Match Between	0.3	10	Ω typ	$V_{\rm D} = 3.5 \text{ V}, \text{ I}_{\rm S} = -10 \text{ mA}$
Channels (ΔR_{ON})	0.5	0.5	Ω max	$\mathbf{v}_{\mathrm{D}} = 0, 0, \mathbf{v}, 1_{\mathrm{S}} = -1 0 \mathrm{mm} 1$
	0.0	0.0	32 max	
LEAKAGE CURRENTS ^{2, 3}				
Source OFF Leakage I _S (OFF)	±0.02		nA typ	$V_{\rm D} = \pm 4.5, V_{\rm S} = \pm 4.5;$
	±0.5	± 2.5	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	±0.02		nA typ	$V_{\rm D} = 0 \text{ V}, 5 \text{ V}, V_{\rm S} = 0 \text{ V}, 5 \text{ V};$
C .	± 0.5	± 2.5	nA max	Test Circuit 2
Channel ON Leakage I _D , I _S (ON)	± 0.04		nA typ	$V_{\rm D} = V_{\rm S} = 0 \text{ V}, 5 \text{ V};$
	±1	± 5	nA max	Test Circuit 3
DIGITAL INPUTS				
Input High Voltage, V _{INH}		2.4	V min	
Input Low Voltage, V _{INL}		0.8	V max	
Input Current				
I _{INL} or I _{INH}	0.005		μA typ	$V_{IN} = V_{INL}$ or V_{INH}
		± 0.5	μA max	
DYNAMIC CHARACTERISTICS ⁴				
	160		ne tun	$R_L = 300 \Omega$, $C_L = 35 pF$;
t _{ON}	220	300	ns typ	$V_{S} = 3 V;$ Test Circuit 4
		300	ns max	5
t _{OFF}	60	100	ns typ	$R_L = 300 \Omega, C_L = 35 pF;$
Devel Defense Males These Delays t	140	180	ns max	$V_{\rm S} = 3 \text{ V}$; Test Circuit 4
Break-Before-Make Time Delay, t_D	50	~	ns typ	$R_{L} = 300 \Omega, C_{L} = 35 pF;$
(ADG453 Only)	5	5	ns min	$V_{S1} = V_{S2} = 3 V;$
	10		<u> </u>	Test Circuit 5
Charge Injection	10		pC typ	$V_{\rm S} = 0 \text{ V}, \text{ R}_{\rm S} = 0 \Omega, \text{ C}_{\rm L} = 1.0 \text{ nF};$
			-	Test Circuit 6
OFF Isolation	65		dB typ	$R_L = 50 \Omega, C_L = 5 pF, f = 1 MHz;$
				Test Circuit 7
Channel-to-Channel Crosstalk	-76		dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$;
				Test Circuit 8
C _S (OFF)	15		pF typ	f = 1 MHz
C _D (OFF)	15		pF typ	f = 1 MHz
$C_{\rm D}, C_{\rm S}$ (ON)	100		pF typ	f = 1 MHz
OWER REQUIREMENTS				V _{DD} = +5.5 V
OWER RESOLUTIONED IS				$V_{DD} = +3.5 V$ Digital Inputs = 0 V or 5 V
I _{DD}	0.0001		μA typ	
TUD	0.0001	5	μA typ μA max	
T	0.0001	5		
I _{SS}		5	μA typ	
т	0.5	5	$\mu A \max$	
IL	0.0001	~	μA typ	XI XI
т А	0.5	5	μA max	$V_{L} = +5.5 V$
I_{GND}^4	0.0001	_	μA typ	
	0.5	5	μA max	$V_{\rm L} = +5.5 \text{ V}$

NOTES

¹Temperature range is as follows: B Version: -40°C to +85°C.

 $^{2}T_{MAX} = +70^{\circ}C.$ $^{3}Tested with dual supplies.$ $^{4}Guaranteed by design, not subject to production test.$ Specifications subject to change without notice.

Truth Table (ADG451/ADG452)

ADG451 In	ADG452 In	Switch Condition
0	1	ON
1	0	OFF

PIN CONFIGURATION (DIP/SOIC)

9 P	(Not to 3 S4 6 D4 7 IN4 8	11 S3 10 D3 9 IN3
-----	------------------------------------	-------------------------

Truth Table (ADG453)

Logic	Switch 1, 4	Switch 2, 3
0	OFF	ON
1	ON	OFF

ORDERING GUIDE

Model	Temperature Range	Package Options*
ADG451BN	-40° C to $+85^{\circ}$ C	N-16
ADG451BR	-40°C to +85°C	R-16A
ADG452BN	-40°C to +85°C	N-16
ADG452BR	-40°C to +85°C	R-16A
ADG453BN	-40°C to +85°C	N-16
ADG453BR	-40°C to +85°C	R-16A

*N = Plastic DIP; R = Small Outline IC (SOIC).

ABSOLUTE MAXIMUM RATINGS¹

 $(T_A = +25^{\circ}C \text{ unless otherwise noted})$ V_{DD} to V_{SS} +44 V V_{DD} to GND-0.3 V to +25 V V_L to GND-0.3 V to V_{DD} + 0.3 V Analog, Digital Inputs² V_{SS} -2 V to V_{DD} +2 V or 30 mA, Whichever Occurs First Continuous Current, S or D 100 mA Peak Current, S or D 300 mA (Pulsed at 1 ms, 10% Duty Cycle max) **Operating Temperature Range** Industrial (B Version)-40°C to +85°C Storage Temperature Range-65°C to +150°C Lead Temperature, Soldering (10 sec) +260°C

SOIC Package, Power Dissipation	600 mW
θ_{JA} Thermal Impedance	77°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	+215°C
Infrared (15 sec)	
ESD	2 kV

NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

²Overvoltages at IN, S or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

CAUTION _

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG451/ADG452/ADG453 feature proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



$\overline{V_{DD}}$	Most positive power supply potential.	V _D (V _S)	Analog voltage on terminals D, S.	
V _{SS}	Most negative power supply potential in dual	C _S (OFF)	"OFF" switch source capacitance.	
	supplies. In single supply applications, it may be connected to GND.	C _D (OFF)	"OFF" switch drain capacitance.	
V		C _D , C _S (ON)	"ON" switch capacitance.	
V _L	Logic power supply (+5 V).	t _{ON}	Delay between applying the digital control input	
GND	Ground (0 V) reference.		and the output switching on. See Test Circuit 4.	
S	Source terminal. May be an input or output.	t _{OFF}	Delay between applying the digital control input	
D	Drain terminal. May be an input or output.		and the output switching off.	
IN	Logic control input.	t _D	"OFF" time or "ON" time measured between	
R _{ON}	Ohmic resistance between D and S.		the 90% points of both switches, when switching from one address state to another. See Test	
ΔR_{ON}	On resistance match between any two channels		Circuit 5.	
	i.e., R _{ON} max – R _{ON} min.	Crosstalk	A measure of unwanted signal coupled through	
$R_{\text{FLAT(ON)}}$	Flatness is defined as the difference between the maximum and minimum value of on-resistance as	Crosstark	from one channel to another as a result of para- sitic capacitance.	
	measured over the specified analog signal range.		-	
I _S (OFF)	Source leakage current with the switch "OFF."	Off Isolation	A measure of unwanted signal coupling through an "OFF" switch.	
I _D (OFF)	Drain leakage current with the switch "OFF."	Charge	A measure of the glitch impulse transferred	
I _D , I _S (ON)	C C		from the digital input to the analog output dur- ing switching.	





Figure 1. On Resistance as a Function of V_D (V_S) for Various Dual Supplies



Figure 2. On Resistance as a Function of V_D (V_S) for Different Temperatures with Dual Supplies

Typical Performance Characteristics-ADG451/ADG452/ADG453



Figure 3. On Resistance as a Function of V_D (V_S) for Various Single Supplies



Figure 4. Leakage Currents as a Function of Temperature



Figure 5. Supply Current vs. Input Switching Frequency



Figure 6. On Resistance as a Function of V_D (V_S) for Different Temperatures with Single Supplies



Figure 7. Leakage Currents as a Function of V_D (V_S)



Figure 8. Off Isolation vs. Frequency







Figure 10. Frequency Response with Switch On

APPLICATION

Figure 11 illustrates a precise, fast, sample-and-hold circuit. An AD845 is used as the input buffer while the output operational amplifier is an AD711. During the track mode, SW1 is closed and the output $V_{\rm OUT}$ follows the input signal $V_{\rm IN}$. In the hold mode, SW1 is opened and the signal is held by the hold capacitor $C_{\rm H}$.



Figure 11. Fast, Accurate Sample-and-Hold Circuit

Due to switch and capacitor leakage, the voltage on the hold capacitor will decrease with time. The ADG451/ ADG452/ADG453 minimizes this droop due to its low leakage specifications. The droop rate is further minimized by the use of a polystyrene hold capacitor. The droop rate for the circuit shown is typically 30 μ V/ μ s.

A second switch, SW2, that operates in parallel with SW1, is included in this circuit to reduce pedestal error. Since both switches will be at the same potential, they will have a differential effect on the op amp AD711, which will minimize charge injection effects. Pedestal error is also reduced by the compensation network R_C and C_C . This compensation network reduces the hold time glitch while optimizing the acquisition time. Using the illustrated op amps and component values, the pedestal error has a maximum value of 5 mV over the ± 10 V input range. Both the acquisition and settling times are 850 ns.

Test Circuits







Test Circuit 1. On Resistance

Test Circuit 2. Off Leakage

Test Circuit 3. On Leakage



Test Circuit 4. Switching Times



Test Circuit 5. Break-Before-Make Time Delay



Test Circuit 6. Charge Injection



Test Circuit 7. Off Isolation



Test Circuit 8. Channel-to-Channel Crosstalk

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).



16-Lead SOIC (R-16A)



C3119a-0-2/98